



# PerF≝T<sup>™</sup>Power Transistor

#### **FEATURES**

- Excellent FOM
- Reliability meets AEC-Q101 requirements
- Wettable flank leads for enhanced AOI
- 100% UIS and Rg tested
- 175°C operating junction temperature
- RoHS Compliant
- Halogen-free

KEY PERFORMANCE PARAMETERS				
PARAMETER		VALUE	UNIT	
V <sub>DS</sub>		100	V	
D (22.5.)	V <sub>GS</sub> = 10V	24		
R <sub>DS(on)</sub> (max)	$V_{GS} = 7V$	28.8	mΩ	
Qg	$V_{GS} = 10V$	8.1	nC	



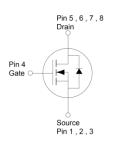




#### **APPLICATIONS**

- Solenoid and motor drivers
- DC-DC converters
- Load Switch
- SMPS





Note: MSL 1 (Moisture Sensitivity Level) per J-STD-020

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		$V_{DS}$	100	V	
Gate-Source Voltage		V <sub>G</sub> s	±20	V	
Continuous Drain Current	T <sub>C</sub> = 25°C		34		
	T <sub>C</sub> = 100°C	l <sub>D</sub>	24	Α	
	T <sub>A</sub> = 25°C		7.5		
Pulsed Drain Current (Note 1)		I <sub>DM</sub>	136	А	
Single Pulse Avalanche Current (Note 2)		las	6.5	А	
Single Pulse Avalanche Energy (Note 2)		Eas	6.3	mJ	
Total Power Dissipation	T <sub>C</sub> = 25°C	Б	63	14/	
	T <sub>C</sub> = 125°C	P <sub>D</sub>	21	W	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	- 55 to +175	°C	

THERMAL PERFORMANCE				
PARAMETER	SYMBOL	LIMIT	UNIT	
Junction to Case Thermal Resistance	Rejc	2.38	°C/W	
Junction to Ambient Thermal Resistance (Note 3)	R <sub>ÐJA</sub>	50	°C/W	

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#### Notes:

- 1. Pulse Width ≤ 100µs.
- 2. L = 0.3mH,  $V_{GS}$  = 10V,  $R_{G}$  = 25 $\Omega$ , Starting  $T_{J}$  = 25 $^{\circ}$ C.
- 3. Device on a PCB FR4 with 1 in<sup>2</sup> (single layer, 2 oz thickness) copper area for drain connection.



PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static						
Drain-Source Breakdown Voltage	$V_{GS} = 0V$ , $I_D = 1mA$	BV <sub>DSS</sub>	100			V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	V <sub>GS(TH)</sub>	2.4	3	3.6	V
Gate Body Leakage	$V_{GS} = \pm 20V, V_{DS} = 0V$	I <sub>GSS</sub>			±100	nA
	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 100V	I <sub>DSS</sub>			1	μA
Drain-Source Leakage Current	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 100V T <sub>J</sub> = 125°C				100	
Drain-Source On-State Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 17A	_		19	24	mΩ
(Note 4)	V <sub>GS</sub> = 7V, I <sub>D</sub> = 17A	R <sub>DS(on)</sub>		23	28.8	
Forward Transconductance (Note 4)	$V_{DS} = 10V, I_D = 4.3A$	<b>G</b> fs		28		S
Dynamic (Note 5)						
Total Gate Charge	$V_{DS} = 50V, I_{D} = 7.5A,$ $V_{GS} = 7V$	$Q_g$		6		nC
Total Gate Charge	$V_{DS} = 50V, I_D = 7.5A,$	Qg		8.1		
Gate-Source Charge		Q <sub>gs</sub>		2.8		nC
Gate-Drain Charge	V <sub>GS</sub> = 10V	Q <sub>gd</sub>		2.1		
Input Capacitance		Ciss		512		
Output Capacitance	$V_{DS} = 60V$ , $V_{GS} = 0V$ ,	Coss		112		pF
Reverse Transfer Capacitance	f = 1.0MHz	Crss		17		
Gate Resistance	f = 1.0MHz	Rg		1.1		Ω
Switching (Note 6)						
Turn-On Delay Time		t <sub>d(on)</sub>		6.4		
Turn-On Rise Time	$V_{DD} = 50V, R_G = 6\Omega,$	t <sub>r</sub>		16		
Turn-Off Delay Time	$I_D = 7.5A$ , $V_{GS} = 10V$	t <sub>d(off)</sub>		10		ns
Turn-Off Fall Time		t <sub>f</sub>		8		
Source-Drain Diode						
Forward Voltage (Note 4)	I <sub>S</sub> = 17A, V <sub>GS</sub> = 0V	VsD			1.1	V
Reverse Recovery Time	Is = 7.5A,	t <sub>rr</sub>		41		ns
Reverse Recovery Charge	di/dt = 100A/µs	Qrr		52		nC

### Notes:

- 4. Pulse test: Pulse Width  $\leq 300 \mu s$ , duty cycle  $\leq 2\%$ .
- 5. Defined by design. Not subject to production test.
- 6. Switching time is essentially independent of operating temperature.

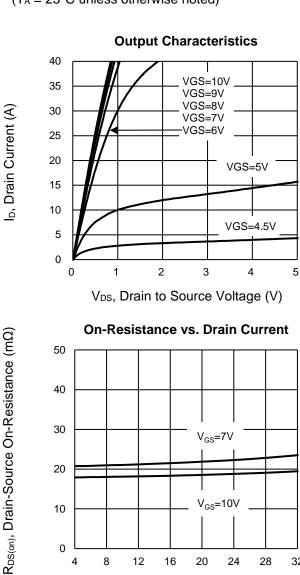
# **ORDERING INFORMATION**

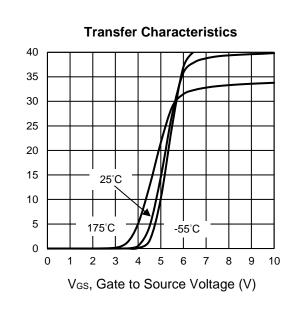
ORDERING CODE	PACKAGE	PACKING
TSM240NH10CR RLG	PDFN56U	2,500pcs / 13" Reel



# **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 



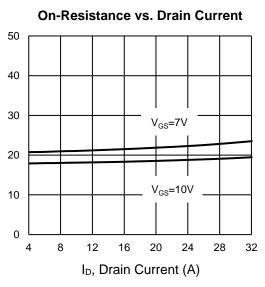


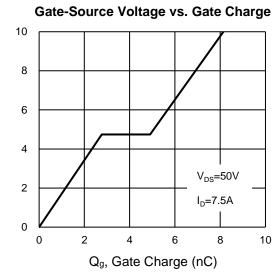
lo, Drain Current (A)

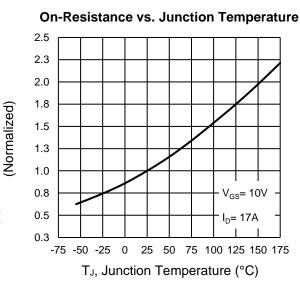
V<sub>GS</sub>, Gate to Source Voltage (V)

 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$ , Drain-Source On-Resistance (m $\Omega$ )

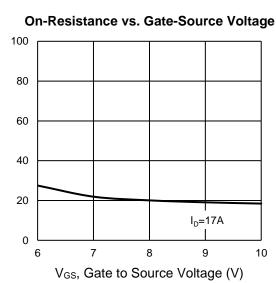
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RDS(on), Drain-Source On-Resistance

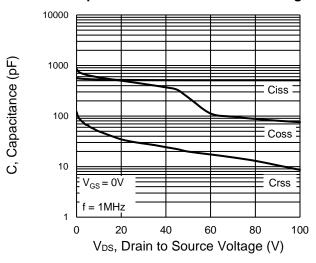




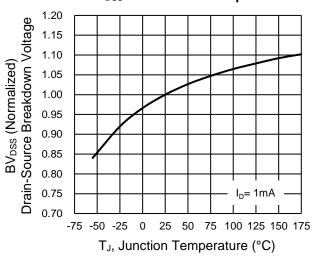
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 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

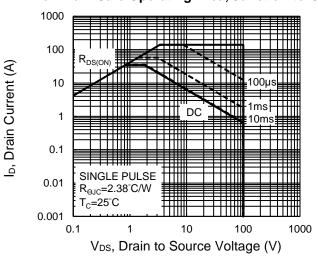




#### BV<sub>DSS</sub> vs. Junction Temperature

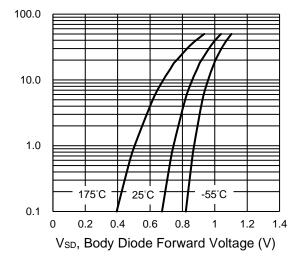


#### Maximum Safe Operating Area, Junction-to-Case



Normalized Effective Transient Thermal Impedance, Zeuc

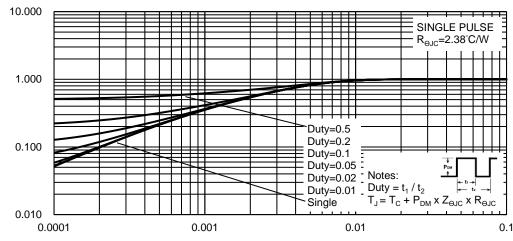
#### Source-Drain Diode Forward Current vs. Voltage



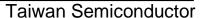
# Normalized Thermal Transient Impedance, Junction-to-Case

Reverse Drain Current (A)

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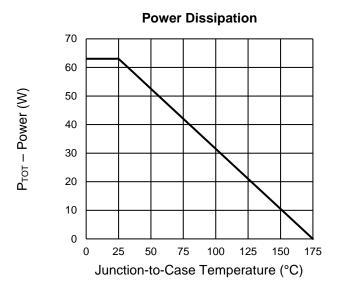
t, Square Wave Pulse Duration (sec)

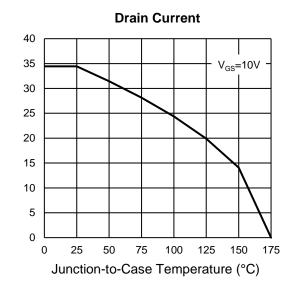




### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

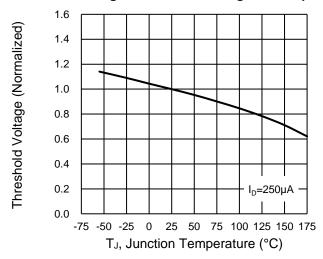


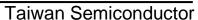


I<sub>D</sub>-Drain Current (A)

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### Normalized gate threshold voltage vs Temperature

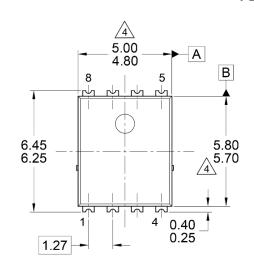


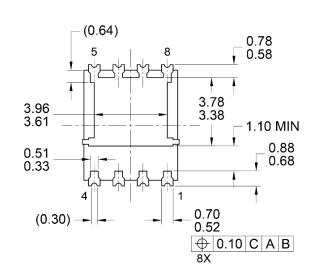


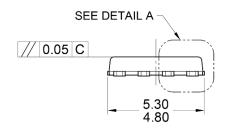


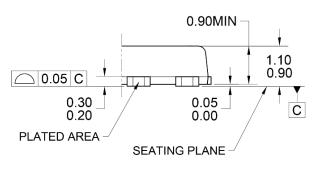
# PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

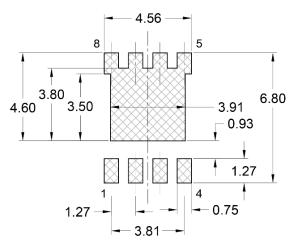
#### PDFN56U











**DETAIL A** (SCALE 2:1)

5 **TSC** 240NH10 YWWLF DOT MARKING, PIN #1 ID

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SUGGESTED PAD LAYOUT (REFERENCE ONLY)

MARKING DIAGRAM

1. ALL DIMENSIONS ARE IN MILLIMETERS.

240NH10 = Device marking = Year code

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2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

> WW = Week code (01~52) L = Lot code  $(1\sim9,A\sim Z)$ F = Factory code

3. PACKAGE OUTLINE REFERENCE: JEITA ED-7500B, EIAJ SC-111BB.

NOTES: UNLESS OTHERWISE SPECIFIED

MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

5. DWG NO. REF: HQ2SD07-PDFN56U-023 REV B.



Taiwan Semiconductor

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